



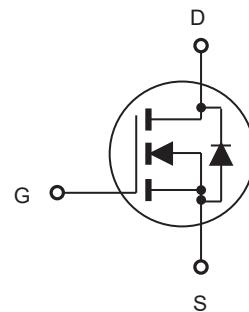
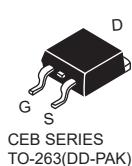
# CEP43N60SF/CEB43N60SF CEF43N60SF

N-Channel Enhancement Mode Field Effect Transistor With Fast Body Diode

## FEATURES

Type	V <sub>DSS</sub> @T <sub>J</sub> max	R <sub>DS(ON)</sub>	I <sub>D</sub>	@V <sub>GS</sub>
CEP43N60SF	650V	68mΩ	43A	10V
CEB43N60SF	650V	68mΩ	43A	10V
CEF43N60SF	650V	68mΩ	43A <sup>d</sup>	10V

- Super high dense cell design for extremely low R<sub>DS(ON)</sub>.
- High power and current handing capability.
- Pb-free lead plating ; RoHS compliant.
- Halogen Free.
- Fast reverse recovery time.



## ABSOLUTE MAXIMUM RATINGS T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V <sub>DS</sub>	600		V
Gate-Source Voltage	V <sub>GS</sub>	±30		V
Drain Current-Continuous @ T <sub>C</sub> = 25°C @ T <sub>C</sub> = 100°C	I <sub>D</sub>	43	43 <sup>d</sup>	A
		27	27 <sup>d</sup>	A
Drain Current-Pulsed <sup>a</sup>	I <sub>DM</sub> <sup>e</sup>	172	172 <sup>d</sup>	A
Maximum Power Dissipation @ T <sub>C</sub> = 25°C - Derate above 25°C	P <sub>D</sub>	297	85	W
		2.37	0.68	W/°C
Single Pulsed Avalanche Energy <sup>g</sup>	E <sub>AS</sub>	200		mJ
Single Pulsed Avalanche Current <sup>g</sup>	I <sub>AS</sub>	20		A
Operating and Store Temperature Range	T <sub>J,T<sub>stg</sub></sub>	-55 to 150		°C

## Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.42	1.47	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62.5	65	°C/W



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## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	600			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 600\text{V}, V_{\text{GS}} = 0\text{V}$			10	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics</b> <sup>b</sup>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	3		5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 21\text{A}$		57	68	$\text{m}\Omega$
Gate Input Resistance	$R_g$	f=1MHz,open Drain		1.9		$\Omega$
<b>Dynamic Characteristics</b> <sup>c</sup>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		3500		pF
Output Capacitance	$C_{\text{oss}}$			130		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			5		pF
<b>Switching Characteristics</b> <sup>c</sup>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$		81		ns
Turn-On Rise Time	$t_r$			102		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			179		ns
Turn-Off Fall Time	$t_f$			64		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 480\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		74		nC
Gate-Source Charge	$Q_{\text{gs}}$			18		nC
Gate-Drain Charge	$Q_{\text{gd}}$			35		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_s$ <sup>f</sup>	$V_{\text{GS}} = 0\text{V}, I_s = 21\text{A}$			43	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$				1.4	V
Reverse Recovery Time	$T_{\text{rr}}$			180		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			1.3		uC

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature .
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$  .
- c.Guaranteed by design, not subject to production testing.
- d.Limited only by maximum temperature allowed .
- e.Pulse width limited by safe operating area .
- f.Full package  $I_{\text{S}(\text{max})} = 22.8\text{A}$  .
- g. $L = 1\text{mH}, I_{\text{AS}} = 20\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .



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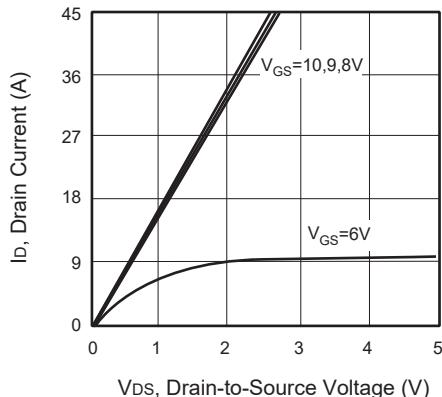


Figure 1. Output Characteristics

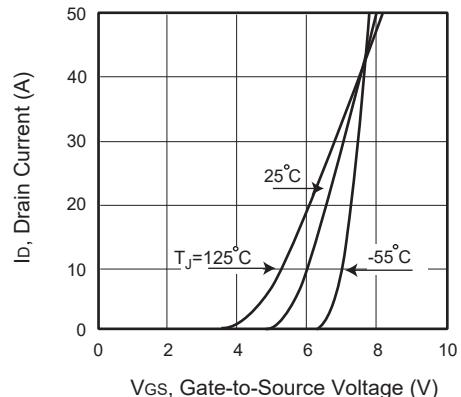


Figure 2. Transfer Characteristics

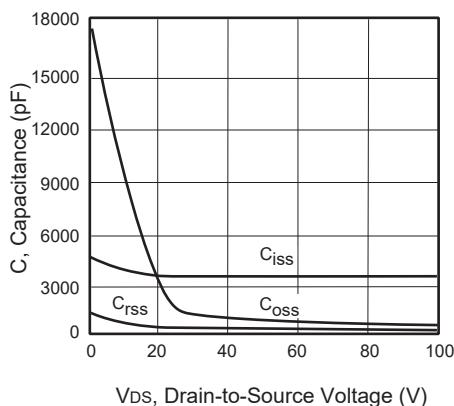


Figure 3. Capacitance

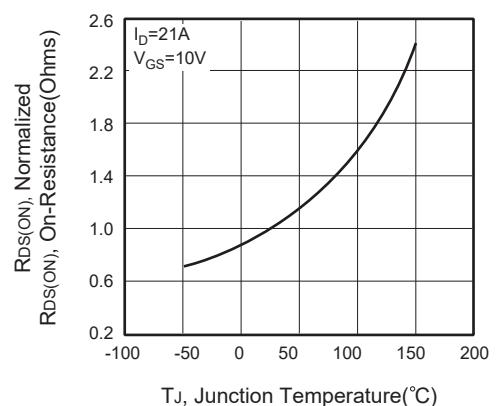


Figure 4. On-Resistance Variation with Temperature

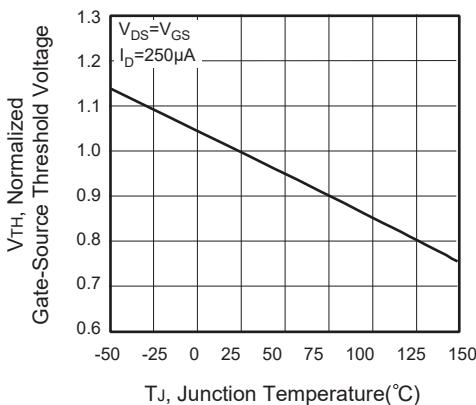


Figure 5. Gate Threshold Variation with Temperature

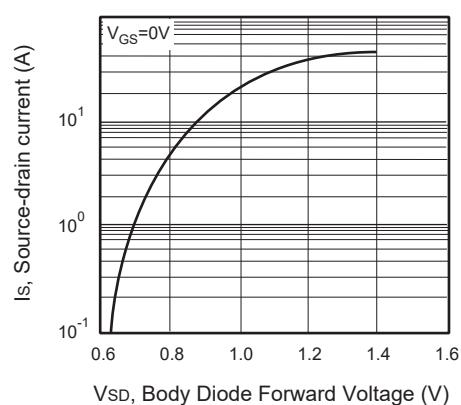


Figure 6. Body Diode Forward Voltage Variation with Source Current



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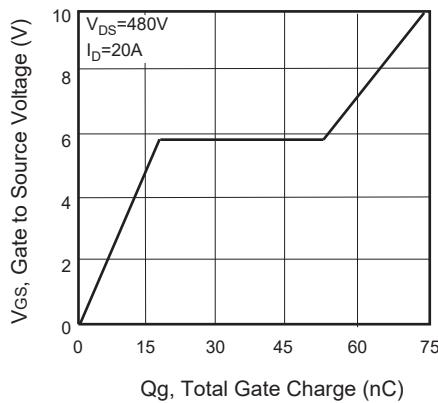


Figure 7. Gate Charge

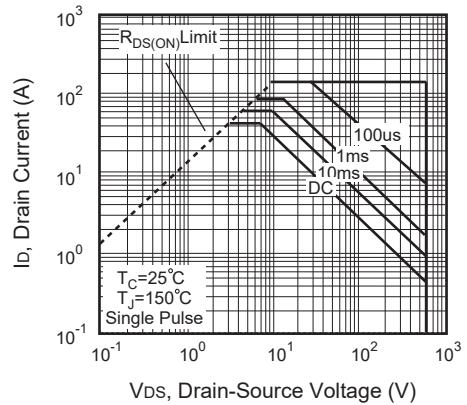


Figure 8. Maximum Safe  
Operating Area

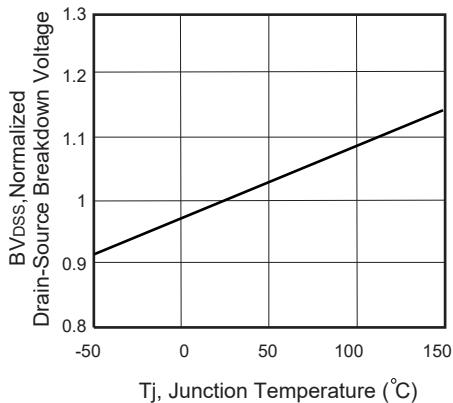


Figure 9. Breakdown Voltage Variation  
VS Temperature

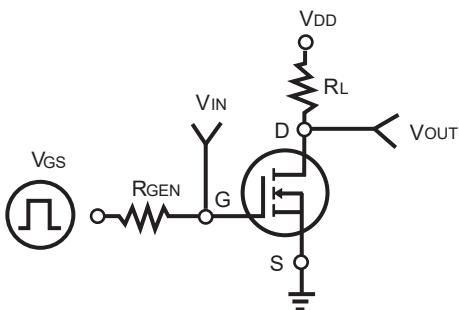


Figure 10. Switching Test Circuit

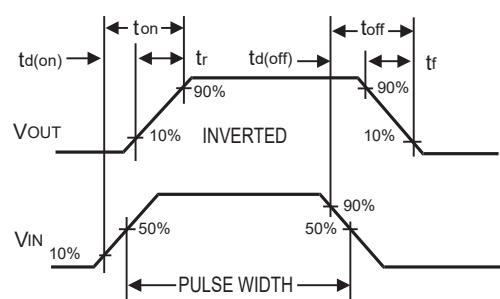


Figure 11. Switching Waveforms



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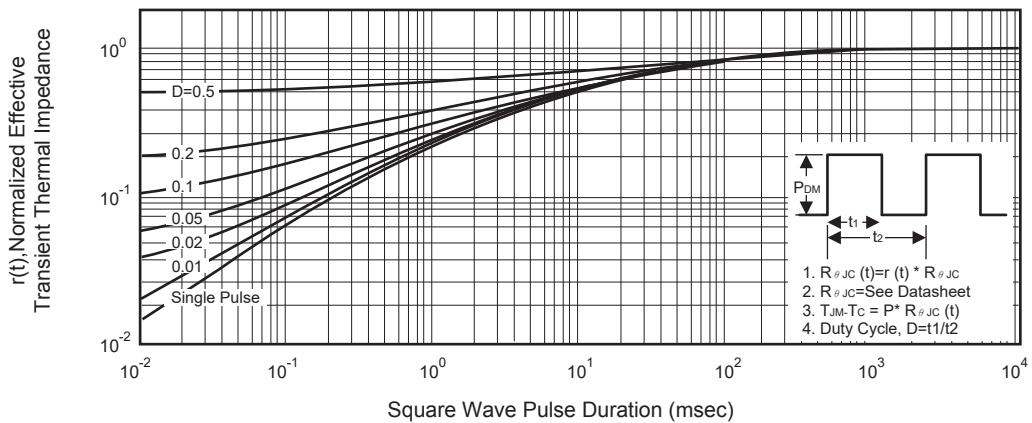


Figure 12. Normalized Thermal Transient Impedance Curve